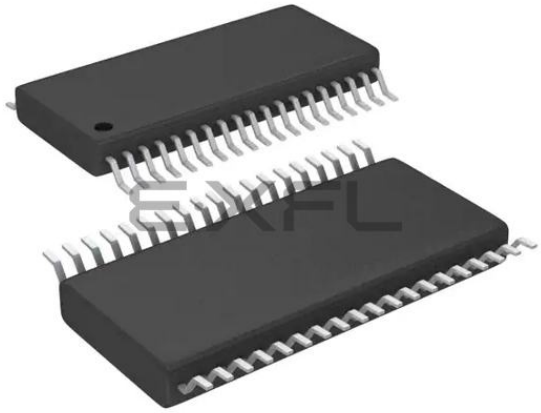

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Discontinued at Digi-Key
Core Processor	XC800
Core Size	8-Bit
Speed	86MHz
Connectivity	LINbus, SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	19
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	38-TFSOP (0.173", 4.40mm Width)
Supplier Device Package	PG-TSSOP-38
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xc866l1fraabkxuma1

1 Summary of Features

- High-performance XC800 Core
  - compatible with standard 8051 processor
  - two clocks per machine cycle architecture (for memory access without wait state)
  - two data pointers
- On-chip memory
  - 8 Kbytes of Boot ROM
  - 256 bytes of RAM
  - 512 bytes of XRAM
  - 4/8/16 Kbytes of Flash; or
    8/16 Kbytes of ROM, with additional 4 Kbytes of Flash
    (includes memory protection strategy)
- I/O port supply at 3.3 V/5.0 V and core logic supply at 2.5 V (generated by embedded voltage regulator)

(further features are on next page)

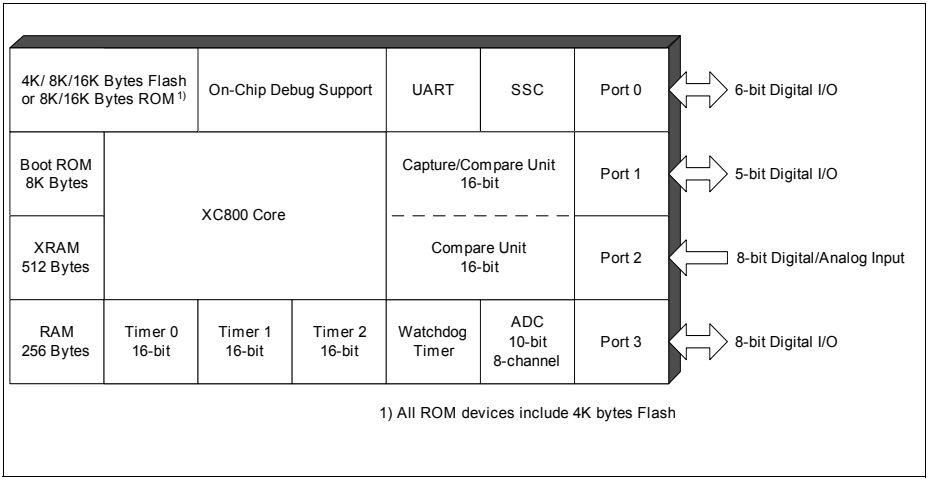

Figure 1 XC866 Functional Units

Features (continued):

- Reset generation
  - Power-On reset
  - Hardware reset
  - Brownout reset for core logic supply
  - Watchdog timer reset
  - Power-Down Wake-up reset
- On-chip OSC and PLL for clock generation
  - PLL loss-of-lock detection
- Power saving modes
  - slow-down mode
  - idle mode
  - power-down mode with wake-up capability via RXD or EXINT0
  - clock gating control to each peripheral
- Programmable 16-bit Watchdog Timer (WDT)
- Four ports
  - 19 pins as digital I/O
  - 8 pins as digital/analog input
- 8-channel, 10-bit ADC
- Three 16-bit timers
  - Timer 0 and Timer 1 (T0 and T1)
  - Timer 2
- Capture/compare unit for PWM signal generation (CCU6)
- Full-duplex serial interface (UART)
- Synchronous serial channel (SSC)
- On-chip debug support
  - 1 Kbyte of monitor ROM (part of the 8-Kbyte Boot ROM)
  - 64 bytes of monitor RAM
- PG-TSSOP-38 pin package
- Temperature range T_A:
  - SAF (-40 to 85 °C)
  - SAK (-40 to 125 °C)

Table 2 Device Summary

	SAK-XC866*-1FRI 3V	3.3	–	4	–	Industrial
	SAF-XC866*-4FRA 3V	3.3	12	4	–	Automotive
	SAF-XC866*-4FRI 3V	3.3	12	4	–	Industrial
	SAF-XC866*-2FRA 3V	3.3	4	4	–	Automotive
	SAF-XC866*-2FRI 3V	3.3	4	4	–	Industrial
	SAF-XC866*-1FRA 3V	3.3	–	4	–	Automotive
	SAF-XC866*-1FRI 3V	3.3	–	4	–	Industrial
ROM	SAK-XC866*-4RRA	5.0	–	4	16	Automotive
	SAK-XC866*-4RRI	5.0	–	4	16	Industrial
	SAK-XC866*-2RRA	5.0	–	4	8	Automotive
	SAK-XC866*-2RRI	5.0	–	4	8	Industrial
	SAF-XC866*-4RRA	5.0	–	4	16	Automotive
	SAF-XC866*-4RRI	5.0	–	4	16	Industrial
	SAF-XC866*-2RRA	5.0	–	4	8	Automotive
	SAF-XC866*-2RRI	5.0	–	4	8	Industrial
	SAK-XC866*-4RRA 3V	3.3	–	4	16	Automotive
	SAK-XC866*-4RRI 3V	3.3	–	4	16	Industrial
	SAK-XC866*-2RRA 3V	3.3	–	4	8	Automotive
	SAK-XC866*-2RRI 3V	3.3	–	4	8	Industrial
	SAF-XC866*-4RRA 3V	3.3	–	4	16	Automotive
	SAF-XC866*-4RRI 3V	3.3	–	4	16	Industrial
	SAF-XC866*-2RRA 3V	3.3	–	4	8	Automotive
	SAF-XC866*-2RRI 3V	3.3	–	4	8	Industrial

1) Industrial is not for Automotive usage

2) The flash memory (P-Flash and D-Flash) can be used for code or data.

*Note: The asterisk (*) above denotes the device configuration letters from **Table 1**.*

Ordering Information

The ordering code for Infineon Technologies microcontrollers provides an exact reference to the required product. This ordering code identifies:

- The derivative itself, i.e. its function set, the temperature range, and the supply voltage
- the package and the type of delivery

For the available ordering codes for the XC866, please refer to your responsible sales representative or your local distributor.

As this document refers to all the derivatives, some descriptions may not apply to a specific product. For simplicity all versions are referred to by the term XC866 throughout this document.

Table 3 Pin Definitions and Functions (cont'd)

Symbol	Pin Number	Type	Reset State	Function
P1		I/O		**Port 1** Port 1 is a 5-bit bidirectional general purpose I/O port. It can be used as alternate functions for the JTAG, CCU6, UART, and the SSC.
P1.0	27		PU	RXD_0 UART Receive Data Input T2EX Timer 2 External Trigger Input
P1.1	28		PU	EXINT3 External Interrupt Input 3 TDO_1 JTAG Serial Data Output TXD_0 UART Transmit Data Output/ Clock Output
P1.5	29		PU	CCPOS0_1 CCU6 Hall Input 0 EXINT5 External Interrupt Input 5 EXF2_0 TImer 2 External Flag Output RXDO_0 UART Transmit Data Output
P1.6	9		PU	CCPOS1_1 CCU6 Hall Input 1 T12HR_0 CCU6 Timer 12 Hardware Run Input EXINT6 External Interrupt Input 6
P1.7	10		PU	CCPOS2_1 CCU6 Hall Input 2 T13HR_0 CCU6 Timer 13 Hardware Run Input P1.5 and P1.6 can be used as a software chip select output for the SSC.

Table 3 Pin Definitions and Functions (cont'd)

Symbol	Pin Number	Type	Reset State	Function	
P3		I		**Port 3** Port 3 is a bidirectional general purpose I/O port. It can be used as alternate functions for the CCU6.	
P3.0	32		Hi-Z	CCPOS1_2 CC60_0	CCU6 Hall Input 1 Input/Output of Capture/Compare channel 0
P3.1	33		Hi-Z	CCPOS0_2 CC61_2 COUT60_0	CCU6 Hall Input 0 Input/Output of Capture/Compare channel 1 Output of Capture/Compare channel 0
P3.2	34		Hi-Z	CCPOS2_2 CC61_0	CCU6 Hall Input 2 Input/Output of Capture/Compare channel 1
P3.3	35		Hi-Z	COUT61_0	Output of Capture/Compare channel 1
P3.4	36		Hi-Z	CC62_0	Input/Output of Capture/Compare channel 2
P3.5	37		Hi-Z	COUT62_0	Output of Capture/Compare channel 2
P3.6	30		PD	$\overline{\text{CTRAP\_0}}$	CCU6 Trap Input
P3.7	31		Hi-Z	EXINT4 COUT63_0	External Interrupt Input 4 Output of Capture/Compare channel 3

3.2 Memory Organization

The XC866 CPU operates in the following five address spaces:

- 8 Kbytes of Boot ROM program memory
- 256 bytes of internal RAM data memory
- 512 bytes of XRAM memory
  (XRAM can be read/written as program memory or external data memory)
- a 128-byte Special Function Register area
- 4/8/16 Kbytes of Flash program memory (Flash devices); or
  8/16 Kbytes of ROM program memory, with additional 4 Kbytes of Flash
  (ROM devices)

Figure 6 illustrates the memory address spaces of the XC866-4FR device.

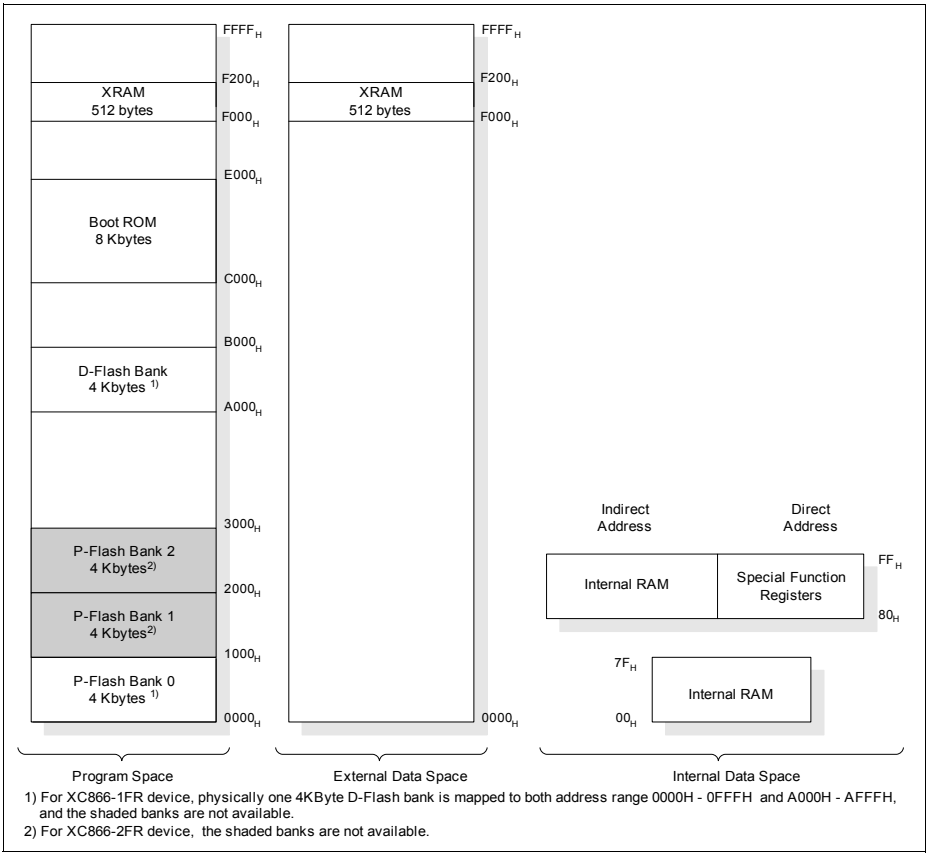

Figure 6 Memory Map of XC866 Flash Devices

Table 8 System Control Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
$B3_H$	**ID** **Reset: 01_H** Identity Register	Bit Field	PRODID					VERID		
		Type	r					r		
$B4_H$	**PMCON0** **Reset: 00_H** Power Mode Control Register 0	Bit Field	0	WDT RST	WKRS	WK SEL	SD	PD	WS	
		Type	r	rwh	rwh	rw	rw	rwh	rw	
$B5_H$	**PMCON1** **Reset: 00_H** Power Mode Control Register 1	Bit Field	0				T2_DIS	CCU _DIS	SSC _DIS	ADC _DIS
		Type	r				rw	rw	rw	rw
$B6_H$	**OSC_CON** **Reset: 08_H** OSC Control Register	Bit Field	0			OSC PD	XPD	OSC SS	ORD RES	OSCR
		Type	r			rw	rw	rw	rwh	rh
$B7_H$	**PLL_CON** **Reset: 20_H** PLL Control Register	Bit Field	NDIV				VCO BYP	OSC DISC	RESLD	LOCK
		Type	rw				rw	rw	rwh	rh
BA_H	**CMCON** **Reset: 00_H** Clock Control Register	Bit Field	VCO SEL	0			CLKREL			
		Type	rw	r			rw			
BB_H	**PASSWD** **Reset: 07_H** Password Register	Bit Field	PASS					PROTE CT_S	MODE	
		Type	w					rh	rw	
BC_H	**FEAL** **Reset: 00_H** Flash Error Address Register Low	Bit Field	ECCERRADDR[7:0]							
		Type	rh							
BD_H	**FEAH** **Reset: 00_H** Flash Error Address Register High	Bit Field	ECCERRADDR[15:8]							
		Type	rh							
BE_H	**COCON** **Reset: 00_H** Clock Output Control Register	Bit Field	0		TLEN	COUT S	COREL			
		Type	r		rw	rw	rw			
$E9_H$	**MISC_CON** **Reset: 00_H** Miscellaneous Control Register	Bit Field	0							DFLAS HEN
		Type	r							rwh
RMAP = 0, Page 3										
$B3_H$	**XADDRH** **Reset: $F0_H$** On-Chip XRAM Address Higher Order	Bit Field	ADDRH							
		Type	rw							

The WDT SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 9 WDT Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 1										
BB_H	**WDTCON** **Reset: 00_H** Watchdog Timer Control Register	Bit Field	0		WINB EN	WDT PR	0	WDT EN	WDT RS	WDT IN
		Type	r		rw	rh	r	rw	rwh	rw
BC_H	**WDTREL** **Reset: 00_H** Watchdog Timer Reload Register	Bit Field	WDTREL							
		Type	rw							
BD_H	**WDTWINB** **Reset: 00_H** Watchdog Window-Boundary Count Register	Bit Field	WDTWINB							
		Type	rw							
BE_H	**WDTL** **Reset: 00_H** Watchdog Timer Register Low	Bit Field	WDT[7:0]							
		Type	rh							
BF_H	**WDTH** **Reset: 00_H** Watchdog Timer Register High	Bit Field	WDT[15:8]							
		Type	rh							

The Port SFRs can be accessed in the standard memory area (RMAP = 0).

Table 10 Port Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
$B2_H$	**PORT_PAGE** **Reset: 00_H** Page Register for PORT	Bit Field	OP		STNR		0	PAGE		
		Type	w		w		r	rwh		
RMAP = 0, Page 0										
80_H	**P0_DATA** **Reset: 00_H** P0 Data Register	Bit Field	0		P5	P4	P3	P2	P1	P0
		Type	r		rwh	rwh	rwh	rwh	rwh	rwh
86_H	**P0_DIR** **Reset: 00_H** P0 Direction Register	Bit Field	0		P5	P4	P3	P2	P1	P0
		Type	r		rw	rw	rw	rw	rw	rw
90_H	**P1_DATA** **Reset: 00_H** P1 Data Register	Bit Field	P7	P6	P5	0			P1	P0
		Type	rwh	rwh	rwh	r			rwh	rwh
91_H	**P1_DIR** **Reset: 00_H** P1 Direction Register	Bit Field	P7	P6	P5	0			P1	P0
		Type	rw	rw	rw	r			rw	rw
$A0_H$	**P2_DATA** **Reset: 00_H** P2 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh
$A1_H$	**P2_DIR** **Reset: 00_H** P2 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$B0_H$	**P3_DATA** **Reset: 00_H** P3 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh
$B1_H$	**P3_DIR** **Reset: 00_H** P3 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
RMAP = 0, Page 1										
80_H	**P0_PUDSEL** **Reset: FF_H** P0 Pull-Up/Pull-Down Select Register	Bit Field	0		P5	P4	P3	P2	P1	P0
		Type	r		rw	rw	rw	rw	rw	rw
86_H	**P0_PUDEN** **Reset: $C4_H$** P0 Pull-Up/Pull-Down Enable Register	Bit Field	0		P5	P4	P3	P2	P1	P0
		Type	r		rw	rw	rw	rw	rw	rw
90_H	**P1_PUDSEL** **Reset: FF_H** P1 Pull-Up/Pull-Down Select Register	Bit Field	P7	P6	P5	0			P1	P0
		Type	rw	rw	rw	r			rw	rw
91_H	**P1_PUDEN** **Reset: FF_H** P1 Pull-Up/Pull-Down Enable Register	Bit Field	P7	P6	P5	0			P1	P0
		Type	rw	rw	rw	r			rw	rw
$A0_H$	**P2_PUDSEL** **Reset: FF_H** P2 Pull-Up/Pull-Down Select Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$A1_H$	**P2_PUDEN** **Reset: 00_H** P2 Pull-Up/Pull-Down Enable Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$B0_H$	**P3_PUDSEL** **Reset: BF_H** P3 Pull-Up/Pull-Down Select Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$B1_H$	**P3_PUDEN** **Reset: 40_H** P3 Pull-Up/Pull-Down Enable Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
RMAP = 0, Page 2										
80_H	**P0_ALTSEL0** **Reset: 00_H** P0 Alternate Select 0 Register	Bit Field	0		P5	P4	P3	P2	P1	P0
		Type	r		rw	rw	rw	rw	rw	rw
86_H	**P0_ALTSEL1** **Reset: 00_H** P0 Alternate Select 1 Register	Bit Field	0		P5	P4	P3	P2	P1	P0
		Type	r		rw	rw	rw	rw	rw	rw
90_H	**P1_ALTSEL0** **Reset: 00_H** P1 Alternate Select 0 Register	Bit Field	P7	P6	P5	0			P1	P0
		Type	rw	rw	rw	r			rw	rw
91_H	**P1_ALTSEL1** **Reset: 00_H** P1 Alternate Select 1 Register	Bit Field	P7	P6	P5	0			P1	P0
		Type	rw	rw	rw	r			rw	rw
$B0_H$	**P3_ALTSEL0** **Reset: 00_H** P3 Alternate Select 0 Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw

Table 11 ADC Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
CA_H	**ADC_RESR0L** **Reset: 00_H** Result Register 0 Low	Bit Field	RESULT[1:0]		0	VF	DRC	CHNR		
		Type	rh		r	rh	rh	rh		
CB_H	**ADC_RESR0H** **Reset: 00_H** Result Register 0 High	Bit Field	RESULT[9:2]							
		Type	rh							
CC_H	**ADC_RESR1L** **Reset: 00_H** Result Register 1 Low	Bit Field	RESULT[1:0]		0	VF	DRC	CHNR		
		Type	rh		r	rh	rh	rh		
CD_H	**ADC_RESR1H** **Reset: 00_H** Result Register 1 High	Bit Field	RESULT[9:2]							
		Type	rh							
CE_H	**ADC_RESR2L** **Reset: 00_H** Result Register 2 Low	Bit Field	RESULT[1:0]		0	VF	DRC	CHNR		
		Type	rh		r	rh	rh	rh		
CF_H	**ADC_RESR2H** **Reset: 00_H** Result Register 2 High	Bit Field	RESULT[9:2]							
		Type	rh							
$D2_H$	**ADC_RESR3L** **Reset: 00_H** Result Register 3 Low	Bit Field	RESULT[1:0]		0	VF	DRC	CHNR		
		Type	rh		r	rh	rh	rh		
$D3_H$	**ADC_RESR3H** **Reset: 00_H** Result Register 3 High	Bit Field	RESULT[9:2]							
		Type	rh							
RMAP = 0, Page 3										
CA_H	**ADC_RESRA0L** **Reset: 00_H** Result Register 0, View A Low	Bit Field	RESULT[2:0]			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
CB_H	**ADC_RESRA0H** **Reset: 00_H** Result Register 0, View A High	Bit Field	RESULT[10:3]							
		Type	rh							
CC_H	**ADC_RESRA1L** **Reset: 00_H** Result Register 1, View A Low	Bit Field	RESULT[2:0]			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
CD_H	**ADC_RESRA1H** **Reset: 00_H** Result Register 1, View A High	Bit Field	RESULT[10:3]							
		Type	rh							
CE_H	**ADC_RESRA2L** **Reset: 00_H** Result Register 2, View A Low	Bit Field	RESULT[2:0]			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
CF_H	**ADC_RESRA2H** **Reset: 00_H** Result Register 2, View A High	Bit Field	RESULT[10:3]							
		Type	rh							
$D2_H$	**ADC_RESRA3L** **Reset: 00_H** Result Register 3, View A Low	Bit Field	RESULT[2:0]			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
$D3_H$	**ADC_RESRA3H** **Reset: 00_H** Result Register 3, View A High	Bit Field	RESULT[10:3]							
		Type	rh							
RMAP = 0, Page 4										
CA_H	**ADC_RCR0** **Reset: 00_H** Result Control Register 0	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CB_H	**ADC_RCR1** **Reset: 00_H** Result Control Register 1	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CC_H	**ADC_RCR2** **Reset: 00_H** Result Control Register 2	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CD_H	**ADC_RCR3** **Reset: 00_H** Result Control Register 3	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CE_H	**ADC_VFCR** **Reset: 00_H** Valid Flag Clear Register	Bit Field	0				VFC3	VFC2	VFC1	VFC0
		Type	r				w	w	w	w
RMAP = 0, Page 5										

Table 13 CCU6 Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
FF_H	**CCU6_TRPCTRH** **Reset: 00_H** Trap Control Register High	Bit Field	TRPPEN	TRPEN13	TRPEN					
		Type	rw	rw	rw					
RMAP = 0, Page 3										
$9A_H$	**CCU6_MCMOUTL** **Reset: 00_H** Multi-Channel Mode Output Register Low	Bit Field	0	R	MCMP					
		Type	r	rh	rh					
$9B_H$	**CCU6_MCMOUTH** **Reset: 00_H** Multi-Channel Mode Output Register High	Bit Field	0		CURH			EXPH		
		Type	r		rh			rh		
$9C_H$	**CCU6_ISL** **Reset: 00_H** Capture/Compare Interrupt Status Register Low	Bit Field	T12PM	T12OM	ICC62F	ICC62R	ICC61F	ICC61R	ICC60F	ICC60R
		Type	rh	rh	rh	rh	rh	rh	rh	rh
$9D_H$	**CCU6_ISH** **Reset: 00_H** Capture/Compare Interrupt Status Register High	Bit Field	STR	IDLE	WHE	CHE	TRPS	TRPF	T13PM	T13CM
		Type	rh	rh	rh	rh	rh	rh	rh	rh
$9E_H$	**CCU6_PISEL0L** **Reset: 00_H** Port Input Select Register 0 Low	Bit Field	ISTRP		ISCC62		ISCC61		ISCC60	
		Type	rw		rw		rw		rw	
$9F_H$	**CCU6_PISEL0H** **Reset: 00_H** Port Input Select Register 0 High	Bit Field	IST12HR		ISPOS2		ISPOS1		ISPOS0	
		Type	rw		rw		rw		rw	
$A4_H$	**CCU6_PISEL2** **Reset: 00_H** Port Input Select Register 2	Bit Field	0						IST13HR	
		Type	r						rw	
FA_H	**CCU6_T12L** **Reset: 00_H** Timer T12 Counter Register Low	Bit Field	T12CVL							
		Type	rwh							
FB_H	**CCU6_T12H** **Reset: 00_H** Timer T12 Counter Register High	Bit Field	T12CVH							
		Type	rwh							
FC_H	**CCU6_T13L** **Reset: 00_H** Timer T13 Counter Register Low	Bit Field	T13CVL							
		Type	rwh							
FD_H	**CCU6_T13H** **Reset: 00_H** Timer T13 Counter Register High	Bit Field	T13CVH							
		Type	rwh							
FE_H	**CCU6_CMPSTATL** **Reset: 00_H** Compare State Register Low	Bit Field	0	CC63ST	CCPOS2	CCPOS1	CCPOS0	CC62ST	CC61ST	CC60ST
		Type	r	rh	rh	rh	rh	rh	rh	rh
FF_H	**CCU6_CMPSTATH** **Reset: 00_H** Compare State Register High	Bit Field	T13IM	COUT63PS	COUT62PS	CC62PS	COUT61PS	CC61PS	COUT60PS	CC60PS
		Type	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh

The SSC SFRs can be accessed in the standard memory area (RMAP = 0).

Table 14 SSC Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
$A9_H$	**SSC_PISEL** **Reset: 00_H** Port Input Select Register	Bit Field	0					CIS	SIS	MIS
		Type	r					rw	rw	rw
AA_H	**SSC_CONL** **Reset: 00_H** Control Register Low *Programming Mode*	Bit Field	LB	PO	PH	HB	BM			
		Type	rw	rw	rw	rw	rw			
	Operating Mode	Bit Field	0				BC			
		Type	r				rh			

For power saving purposes, the clocks may be disabled or slowed down according to **Table 23**.

Table 23 System frequency (f_{sys} = 80 MHz)

Power Saving Mode	Action
Idle	Clock to the CPU is disabled.
Slow-down	Clocks to the CPU and all the peripherals, including CCU6, are divided by a common programmable factor defined by bit field CMCON.CLKREL.
Power-down	Oscillator and PLL are switched off.

- 8-bit reload value (BR_VALUE) for the baud rate timer defined by register BG

The following formulas calculate the final baud rate without and with the fractional divider respectively:

$$\text{baud rate} = \frac{f_{PCLK}}{16 \times 2^{BRPRE} \times (BR\_VALUE + 1)} \quad \text{where} \quad 2^{BRPRE} \times (BR\_VALUE + 1) > 1$$

$$\text{baud rate} = \frac{f_{PCLK}}{16 \times 2^{BRPRE} \times (BR\_VALUE + 1)} \times \frac{STEP}{256}$$

The maximum baud rate that can be generated is limited to $f_{PCLK}/32$. Hence, for a module clock of 26.7 MHz, the maximum achievable baud rate is 0.83 MBaud.

Standard LIN protocal can support a maximum baud rate of 20kHz, the baud rate accuracy is not critical and the fractional divider can be disabled. Only the prescaler is used for auto baud rate calculation. For LIN fast mode, which supports the baud rate of 20kHz to 115.2kHz, the higher baud rates require the use of the fractional divider for greater accuracy.

Table 26 lists the various commonly used baud rates with their corresponding parameter settings and deviation errors. The fractional divider is disabled and a module clock of 26.7 MHz is used.

Table 26 Typical Baud rates for UART with Fractional Divider disabled

Baud rate	Prescaling Factor (2^{BRPRE})	Reload Value (BR_VALUE + 1)	Deviation Error
19.2 kBaud	1 (BRPRE=000_B)	87 (57_H)	-0.22 %
9600 Baud	1 (BRPRE=000_B)	174 (AE_H)	-0.22 %
4800 Baud	2 (BRPRE=001_B)	174 (AE_H)	-0.22 %
2400 Baud	4 (BRPRE=010_B)	174 (AE_H)	-0.22 %

The fractional divider allows baud rates of higher accuracy (lower deviation error) to be generated. **Table 27** lists the resulting deviation errors from generating a baud rate of

For module clock f_{ADC} = 26.7 MHz, the analog clock f_{ADCI} frequency can be selected as shown in **Table 30**.

Table 30 f_{ADCI} Frequency Selection

Module Clock f_{ADC}	CTC	Prescaling Ratio	Analog Clock f_{ADCI}
26.7 MHz	00_B	÷ 2	13.3 MHz (N.A)
	01_B	÷ 3	8.9 MHz
	10_B	÷ 4	6.7 MHz
	11_B (default)	÷ 32	833.3 kHz

As f_{ADCI} cannot exceed 10 MHz, bit field CTC should not be set to 00_B when f_{ADC} is 26.7 MHz. During slow-down mode where f_{ADC} may be reduced to 13.3 MHz, 6.7 MHz etc., CTC can be set to 00_B as long as the divided analog clock f_{ADCI} does not exceed 10 MHz. However, it is important to note that the conversion error could increase due to loss of charges on the capacitors, if f_{ADC} becomes too low during slow-down mode.

3.18.2 ADC Conversion Sequence

The analog-to-digital conversion procedure consists of the following phases:

- Synchronization phase (t_{SYN})
- Sample phase (t_S)
- Conversion phase
- Write result phase (t_{WR})

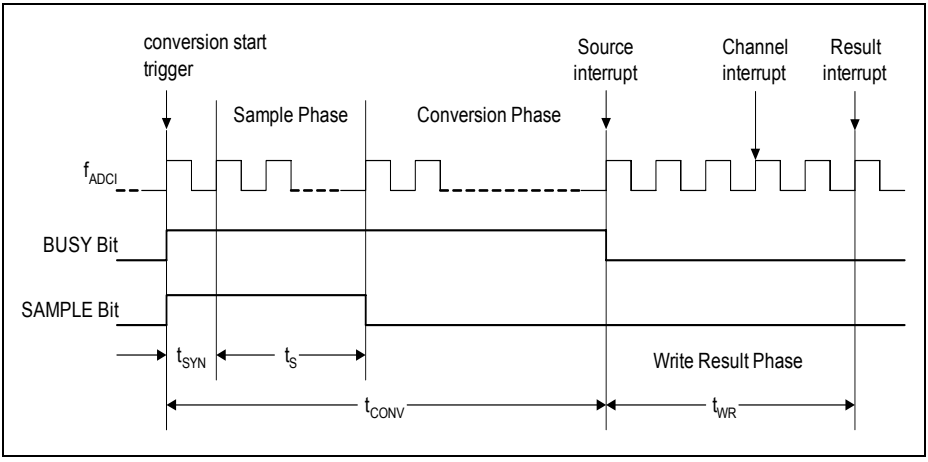

Figure 34 ADC Conversion Timing

4.2 DC Parameters

4.2.1 Input/Output Characteristics

Table 34 Input/Output Characteristics (Operating Conditions apply)

Parameter	Symbol		Limit Values		Unit	Test Conditions Remarks
			min.	max.		
V_{DDP} = 5V Range						
Output low voltage	V_{OL}	CC	–	1.0	V	I_{OL} = 15 mA
			–	0.4	V	I_{OL} = 5 mA
Output high voltage	V_{OH}	CC	V_{DDP} - 1.0	–	V	I_{OH} = -15 mA
			V_{DDP} - 0.4	–	V	I_{OH} = -5 mA
Input low voltage on port pins (all except P0.0 & P0.1)	V_{ILP}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on P0.0 & P0.1	V_{ILP0}	SR	-0.2	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on $\overline{\text{RESET}}$ pin	V_{ILR}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on TMS pin	V_{ILT}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input high voltage on port pins (all except P0.0 & P0.1)	V_{IHP}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on P0.0 & P0.1	V_{IHP0}	SR	0.7 × V_{DDP}	V_{DDP}	V	CMOS Mode
Input high voltage on $\overline{\text{RESET}}$ pin	V_{IHR}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on TMS pin	V_{IHT}	SR	0.75 × V_{DDP}	–	V	CMOS Mode
Input Hysteresis[1] on Port pins	HYS	CC	0.08 × V_{DDP}	–	V	CMOS Mode
Input Hysteresis[1] on XTAL1	$HYSX$	CC	0.07 × V_{DDC}	–	V	

4.2.2 Supply Threshold Characteristics

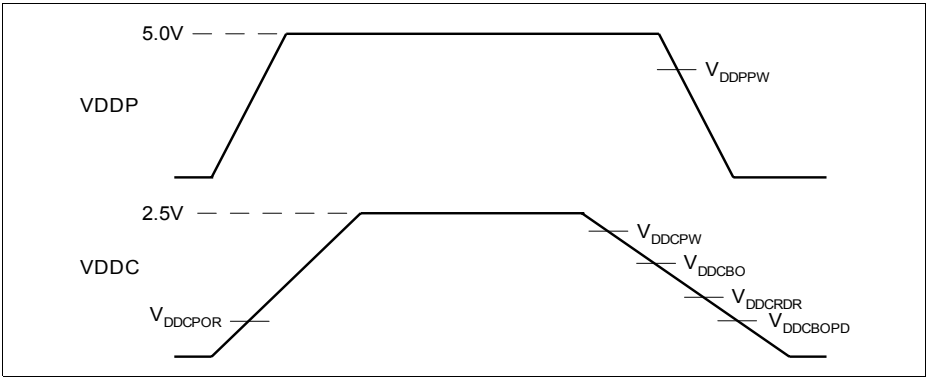

Figure 36 Supply Threshold Parameters

Table 35 Supply Threshold Parameters (Operating Conditions apply)

Parameters	Symbol		Limit Values			Unit	Remarks
			min.	typ.	max.		
V_{DDC} prewarning voltage[1]	V_{DDCPW}	CC	2.2	2.3	2.4	V	
V_{DDC} brownout voltage in active mode[1]	V_{DDCBO}	CC	2.0	2.1	2.2	V	XC866-4FR, XC866-2FR
			2.0	2.1	2.3	V	XC866-1FR, ROM device
RAM data retention voltage	V_{DDCRDR}	CC	0.9	1.0	1.1	V	
V_{DDC} brownout voltage in power-down mode[2]	$V_{DDCBOPD}$	CC	1.3	1.5	1.7	V	
V_{DDP} prewarning voltage[3]	V_{DDPPW}	CC	3.4	4.0	4.6	V	
Power-on reset voltage[2][4]	V_{DDCPOR}	CC	1.3	1.5	1.7	V	

1) Detection is disabled in power-down mode.

2) Detection is enabled in both active and power-down mode.

3) Detection is enabled for external power supply of 5.0V.
Detection must be disabled for external power supply of 3.3V.

4) The reset of EVR is extended by 300 µs typically after the VDDC reaches the power-on reset voltage.

Table 39 Power Supply Current Parameters (Operating Conditions apply; V_{DDP} = 3.3V range)

Parameter	Symbol	Limit Values		Unit	Test Condition Remarks
		typ.[1]	max.[2]		
V_{DDP} = 3.3V Range					
Active Mode	I_{DDP}	21.5	23.3	mA	[3]
Idle Mode	I_{DDP}	16.4	18.9	mA	XC866-4FR, XC866-2FR [4]
		11.2	13.5	mA	XC866-1FR, ROM device [4]
Active Mode with slow-down enabled	I_{DDP}	6.8	8	mA	XC866-4FR, XC866-2FR [5]
		5.4	7.3	mA	XC866-1FR, ROM device [5]
Idle Mode with slow-down enabled	I_{DDP}	6.8	7.8	mA	XC866-4FR, XC866-2FR [6]
		4.9	6.9	mA	XC866-1FR, ROM device [6]

1) The typical I_{DDP} values are periodically measured at T_A = + 25 °C and V_{DDP} = 3.3 V.

2) The maximum I_{DDP} values are measured under worst case conditions (T_A = + 125 °C and V_{DDP} = 3.6 V).

3) I_{DDP} (active mode) is measured with: CPU clock and input clock to all peripherals running at 26.7 MHz(set by on-chip oscillator of 10 MHz and NDIV in PLL_CON to 0010_B), $\overline{RESET}$ = V_{DDP}, no load on ports.

4) I_{DDP} (idle mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 26.7 MHz, $\overline{RESET}$ = V_{DDP}, no load on ports.

5) I_{DDP} (active mode with slow-down mode) is measured with: CPU clock and input clock to all peripherals running at 833 KHz by setting CLKREL in CMCON to 0101_B, $\overline{RESET}$ = V_{DDP}, no load on ports.

6) I_{DDP} (idle mode with slow-down mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enable and running at 833 KHz by setting CLKREL in CMCON to 0101_B,, $\overline{RESET}$ = V_{DDP}, no load on ports.

4.3.4 On-Chip Oscillator Characteristics

Table 43 On-chip Oscillator Characteristics (Operating Conditions apply)

Parameter	Symbol	Limit Values			Unit	Test Conditions
		min.	typ.	max.		
Nominal frequency	f_{NOM} CC	9.75	10	10.25	MHz	under nominal conditions[1] after IFX-backend trimming
Long term frequency deviation[2]	Δf_{LT} CC	-5.0	–	5.0	%	with respect to f_{NOM}, over lifetime and temperature (–10°C to 125°C), for one device after trimming
		-6.0	–	0	%	with respect to f_{NOM}, over lifetime and temperature (–40°C to -10°C), for one device after trimming
Short term frequency deviation	Δf_{ST} CC	-1.0	–	1.0	%	with respect to f_{NOM}, within one LIN message (<10 ms .... 100 ms)

1) Nominal condition: V_{DDC} = 2.5 V, T_A = + 25°C.

2) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

5 Package and Reliability

5.1 Package Parameters (PG-TSSOP-38)

Table 47 provides the thermal characteristics of the package.

Table 47 Thermal Characteristics of the Package

Parameter	Symbol		Limit Values		Unit	Notes
			Min.	Max.		
Thermal resistance junction case[1)]	R_{TJC}	CC	–	15.7	K/W	–
Thermal resistance junction lead[1)]	R_{TJL}	CC	–	39.2	K/W	–

1) The thermal resistances between the case and the ambient (R_{TCA}) , the lead and the ambient (R_{TLA}) are to be combined with the thermal resistances between the junction and the case (R_{TJC}), the junction and the lead (R_{TJL}) given above, in order to calculate the total thermal resistance between the junction and the ambient (R_{TJA}). The thermal resistances between the case and the ambient (R_{TCA}), the lead and the ambient (R_{TLA}) depend on the external system (PCB, case) characteristics, and are under user responsibility.
The junction temperature can be calculated using the following equation: $T_J=T_A + R_{TJA} \times P_D$, where the R_{TJA} is the total thermal resistance between the junction and the ambient. This total junction ambient resistance R_{TJA} can be obtained from the upper four partial thermal resistances, by
a) simply adding only the two thermal resistances (junction lead and lead ambient), or
b) by taking all four resistances into account, depending on the precision needed.

5.3 Quality Declaration

Table 48 shows the characteristics of the quality parameters in the XC866.

Table 48 Quality Parameters

Parameter	Symbol	Limit Values		Unit	Notes
		Min.	Max.		
ESD susceptibility according to Human Body Model (HBM)	V_{HBM}	–	2000	V	Conforming to EIA/JESD22-A114-B
ESD susceptibility according to Charged Device Model (CDM) pins	V_{CDM}	–	500	V	Conforming to JESD22-C101-C